

Report NO.: MG00001000025

**1. Product information****Supplier :** JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

<b>Part Number :</b>	CJB120SN08
<b>Package Type :</b>	TO-263-2L

**2. MATERIAL ANALYSIS DATA SHEET**

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.41%
Lead Frame	Iron	7439-89-6	0.06%	
	Phosphorus	7723-14-0	0.04%	
	Copper	7440-50-8	99.90%	
	Silver	7440-22-4	0.01%	
Wire1	aluminium	7429-90-5	100.00%	3.58%
Wire2	Copper	7440-50-8	100.00%	0.57%
Soft Solder	Lead	7439-92-1	92.50%	3.01%
	Tin	7440-31-5	5.00%	
	Silver	7440-22-4	2.50%	
Mold Compound	Epoxy Resin A	Trade Secret	7.12%	30.40%
	Epoxy Resin B	29690-82-2	4.91%	
	Phenol Resin	Trade Secret	4.41%	
	Silica(Amorphous) A	60676-86-0	74.68%	
	Silica(Amorphous) B	7631-86-9	8.12%	
	Carbon Black	1333-86-4	0.76%	
Plating	Tin	7440-31-5	100.00%	13.61%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.